





SPECIFICATION FOR 3.3V CMOS SMT TCXO MtronPTI P/N M6300S110

Electrical Specifications:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		50.000000		MHz	
Frequency Tolerance		-1.0		+1.0	ppm	@ +25°C
		F	requency Sta	ability		
vs. Temperature	Δ F/F			4.6	ppm	(Max-Min)/2
vs. Aging		-3		+3	ppm	1 st year
vs. Aging		-1		+1	ppm	Per year thereafter.
			RF Outpu	It		
Output Type		HC	CMOS Compati	ble		
Output Load				15	pF	
Symmetry (duty cycle)	T _{DC}	45		55	%	Ref. to 1/2 VDD
Logic "1" Level	V _{OH}	80% V _{DD}			V	HCMOS load
Logic "0" Level	V _{OL}			20% V _{DD}	V	HCMOS load
Rise/Fall Time	T _R /T _F			6	ns	From 20% to 80% V _{DD}
	S	Supply Vo	Itage & Powe	r Consum	ption	
Operating Voltage	Vcc	3.135	3.300	3.465	V	
Operating Current	Icc			90	mA	

Environmental Conditions:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Operating Temperature	TA	-55		+125	°C	
Storage Temperature	Ts	-55		+125	°C	
Shock	Per MIL-S	TD-202, M	ethod 213, Con	dition C (10	0 g's, 6 ms (duration, ½ sinewave)
Vibration	Per MIL-S	TD-202, M	ethod 201 & 20	4 (10 g's fro	om 10-2000	Hz)
Thermal Shock	Per MIL-S	TD-883, M	ethod 1011, Co	ndition A		
Thermal Cycle	Per MIL-STD-883, Method 1010, Condition B					
Hermeticity	Per MIL-S	TD-202, M	ethod 112 (1 x 1	10 ⁻⁸ atm cc/	's of helium)	
Moisture Sensitivity Level (MSL)	MSL 1					
Solderability	Per EIAJ-STD-002					
Max. Soldering Conditions	See Figure	e 1.				
Package Type	pe Type 6-pad 5.0 X 7.0 X 1.9 mm leadless ceramic. RoHS compliant.					

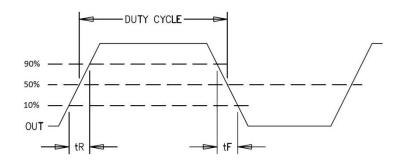




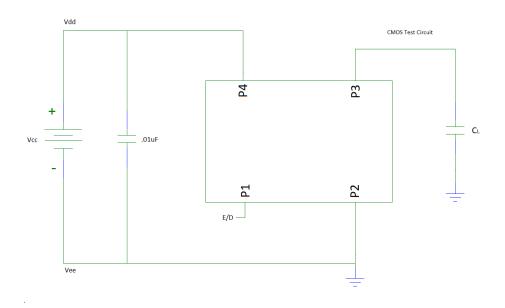


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Output Waveform:



Typical Test Circuit & Load Circuit Diagrams:



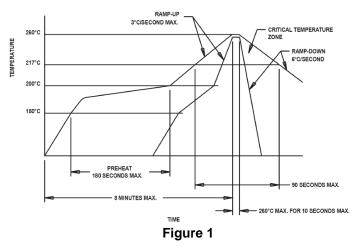




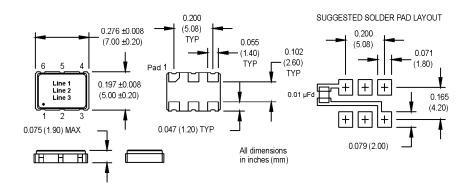


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Soldering Conditions:



Mechanical, Marking, and Pin Out Information:



Datasheet Revision Table:

Date	Rev.	Author	Details of Revision			
06/15/18	0	MM	Original release.			